

N-Channel Enhancement MOSFET

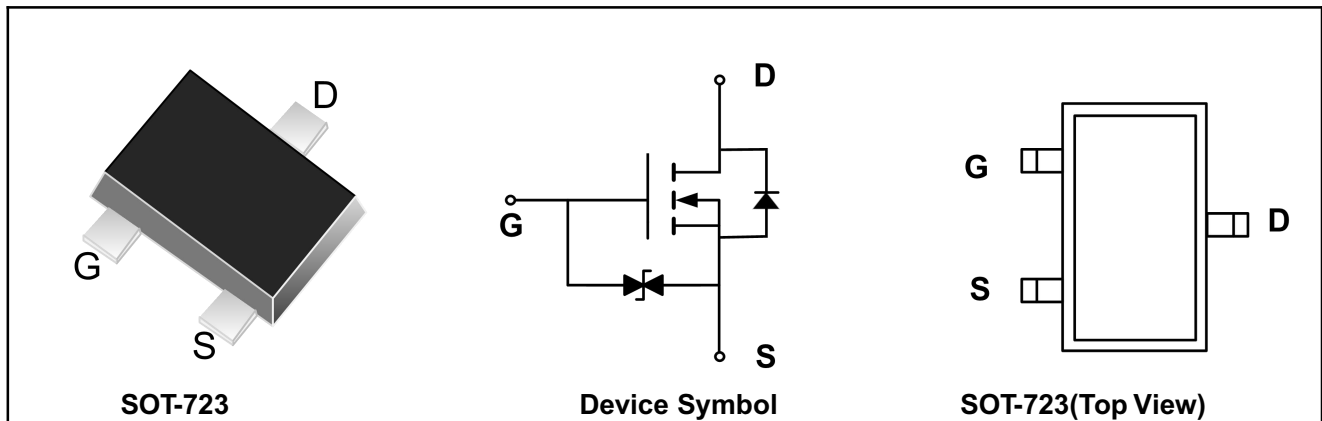
Features

- Small Signal MOSFET
- $V_{DS} = 20V$, $I_D = 0.75A$
 - $R_{DS(on)} < 0.38\Omega$ @ $V_{GS} = 4.5V$
 - $R_{DS(on)} < 0.45\Omega$ @ $V_{GS} = 2.5V$
- Trench LV MOSFET Technology
- ESD Protected

Mechanical Characteristics

- SOT-723 Package
- Marking : Making Code
- RoHS Compliant

Schematic & PIN Configuration



Absolute Maximum Ratings ($T_A = 25^\circ C$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current	I_D	0.75	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	3	A
Power Dissipation	P_D	150	mW
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$
Thermal Resistance from Junction to Ambient ⁽²⁾	$R_{\theta JA}$	833	$^\circ C/W$

EM02N08H

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	B _{VDSS}	V _{GS} = 0V, I _D = 250μA	20	-	-	V
Gate-body Leakage Current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±10V	-	-	±20	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} = 0V	-	-	1	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.35	0.75	1.1	V
Drain-Source On-state Resistance ⁽³⁾	R _{DS(on)}	V _{GS} = 4.5V, I _D = 0.65A	-	0.19	0.38	Ω
		V _{GS} = 2.5V, I _D = 0.55A	-	0.29	0.45	
		V _{GS} = 1.8V, I _D = 0.45A	-	0.70	-	
Dynamic Characteristics ⁽⁴⁾						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 10V, f = 1MHz	-	26.5	-	pF
Output Capacitance	C _{oss}		-	11	-	
Reverse Transfer Capacitance	C _{rss}		-	5.2	-	
Switching Characteristics ⁽⁴⁾						
Turn-on Delay Time	t _{d(on)}	V _{GS} =4.5V, V _{DD} =10V, I _D =0.65A, R _G =3Ω	-	6.7	-	ns
Rise Time	t _r		-	4.8	-	
Turn-off Delay Time	t _{d(off)}		-	17.3	-	
Fall Time ⁽⁴⁾	t _f		-	7.4	-	
Source-Drain Diode Characteristics						
Body Diode Voltage	V _{SD}	I _S =0.15A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	I _S		-	-	0.75	A

Note1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)} = 150°C.

Note2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

Note3. Pulse Test: Pulse width ≤ 300μs, duty cycle ≤ 2%.

Note4. This value is guaranteed by design hence it is not included in the production test.

EM02N08H

Typical Characteristics

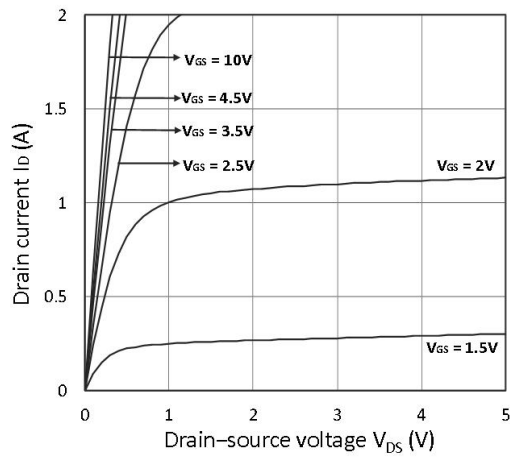


Figure 1. Output Characteristics

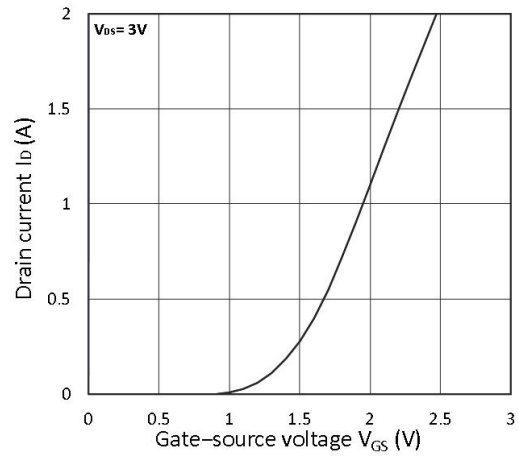


Figure 2. Transfer Characteristics

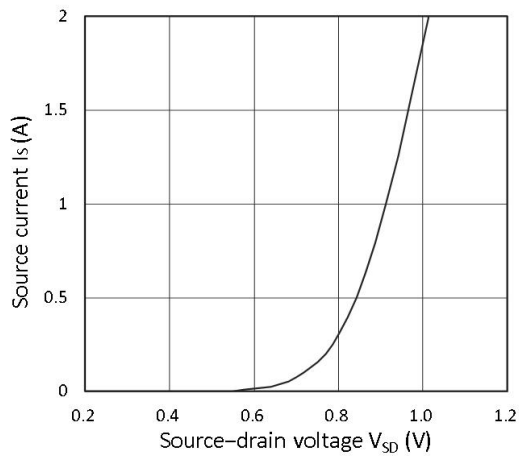


Figure 3. Forward Characteristics of Reverse

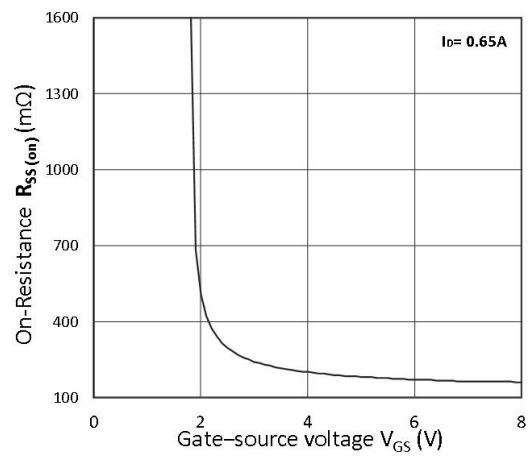


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

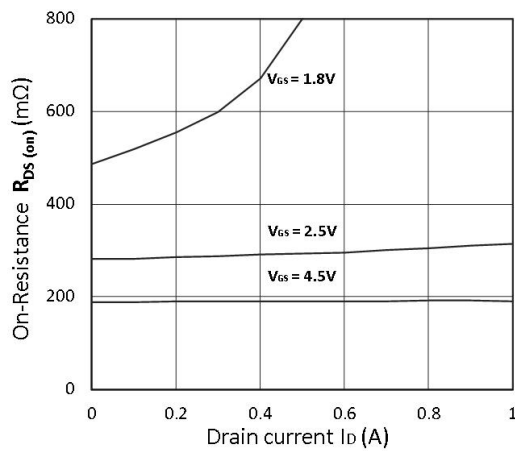


Figure 5. $R_{DS(ON)}$ vs. I_D

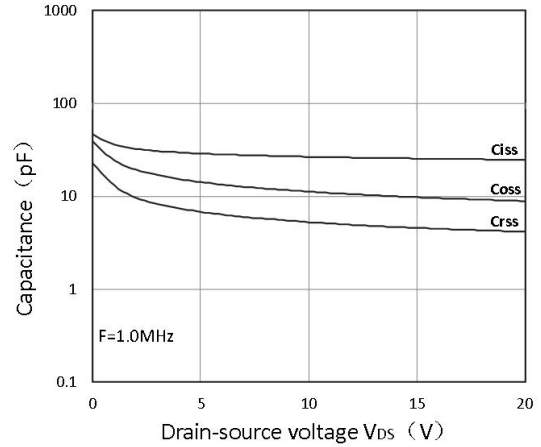


Figure 6. Capacitance Characteristics

EM02N08H

Package Dimension

SOT-723

Package Outline

The package outline diagrams show a top view with dimensions D (total width), b1 (inner width), L (height of the central pad), E1 (height of the side pads), E (total height), b (width of the side pads), and e (distance from the center to the side pads). A side view shows the height A and the lead angle theta. An end view shows the width C.

COMMON DIMENSIONS

SYM BOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
L	0.15	0.25	0.006	0.010
C	0.08	0.17	0.003	0.007
D	1.15	1.25	0.045	0.049
E	1.15	1.25	0.045	0.049
E1	0.75	0.85	0.030	0.033
e	0.40 BSC		0.016 BSC	
θ	0°	10°	0°	10°

Recommended Land Pattern

The recommended land pattern diagram shows a top view with dimensions b (width of the central pad), C (height of the central pad), e (distance from the center to the side pads), e1 (width of the side pads), and M (height of the side pads).

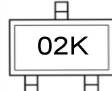
DIMENSIONS

DIM	MILLIMETERS	INCHES
C	0.40	0.0157
M	1.0	0.039
e	0.40	0.0157
e1	0.80	0.0314
b	0.40	0.0157

Notes

1. Dimensioning and tolerances per ANSI Y14.5M, 1985.
2. Controlling Dimension: Millimeters.

Ordering Information

Part	Package	Marking	Packing Information
EM02N08H	SOT-723		8k/Reel

EM02N08H

Revision History and Checking Table

Version	Date	Revision Item	Modifier	Function & Spec Checking	Package & Tape Checking
1.0	2018-05-08	Released Version	Liu Jia Ying	Qi Shu Kun	Liu Jia Ying
1.1	2022-12-28	Update Typeset and package size spec	Yin Peng	Qi Shu Kun	Liu Jia Ying